

Electronic Patent Application Fee Transmittal

Application Number:	10570669
Filing Date:	06-Mar-2006
Title of Invention:	SOI WAFER AND ITS MANUFACTURING METHOD
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Filer:	Arnold Turk/Sean Shoolbraid
Attorney Docket Number:	P29121

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
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Total in USD (\$)				1810